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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/533,291	02/07/2006	Paul Colfer	200316610-2	6028
22879 7590 10/20/2008 HEWLETT PACKARD COMPANY P O BOX 272400, 3404 E. HARMONY ROAD INTELLECTUAL PROPERTY ADMINISTRATION FORT COLLINS, CO 80527-2400				
EXAMINER HO, ANTHONY				
ART UNIT		PAPER NUMBER		
2815				
NOTIFICATION DATE		DELIVERY MODE		
10/20/2008		ELECTRONIC		

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Notice of the Office communication was sent electronically on above-indicated "Notification Date" to the following e-mail address(es):

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Office Action Summary

Application No.

10/533,291

Applicant(s)

COLFER ET AL.

Examiner

ANTHONY HO

Art Unit

2815

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --
Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 24 September 2008.
- 2a) ☒ This action is **FINAL**. 2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1-20, 22-30, 63, 64, 68, 71, 74 and 75 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 1-20, 22-30, 63, 64, 68, 71, 74 and 75 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some * c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
 2. ☐ Certified copies of the priority documents have been received in Application No. _____.
 3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- 1) ☐ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) ☐ Information Disclosure Statement(s) (PTO/SB/08)
Paper No(s)/Mail Date _____
- 4) ☐ Interview Summary (PTO-413)
Paper No(s)/Mail Date _____
- 5) ☐ Notice of Informal Patent Application
- 6) ☐ Other: _____

DETAILED ACTION

This is in response to amendment to application no. 10/533,291 filed on September 24, 2008.

Claims 1-20, 22-30, 63, 64, 68, 71, 74 and 75 are presented for examination.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 1-20, 22-30, 63-64, 68, 71, and 74-75 are rejected under 35 U.S.C. 102(b) as anticipated by or, in the alternative, under 35 U.S.C. 103(a) as obvious over Yudasaka et al (EP 1085578).

In re claims 1-3, Yudasaka et al discloses a method of manufacturing an electronic component comprising at least one n- or p-doped portion, comprising the steps of: co-depositing semi-conducting nanoparticles as a solid in liquid suspension and dopant on a substrate, the nanoparticles comprising silicon element or germanium element; fusing in situ on the substrate the nanoparticles by heating to form a continuous layer through

a physical change of melting; and recrystallizing the continuous layer (paragraph 0004; paragraph 0045 – paragraph 0066).

In re claims 4-6, Yudasaka et al discloses the step of fusing and/or recrystallizing is carried out in a reducing atmosphere (paragraph 0065).

In re claims 7-10, Yudasaka et al discloses the step of heating using laser pulses and cooling (paragraph 0045 – paragraph 00070).

In re claims 11-13, Yudasaka et al discloses the nanoparticles are deposited in a suspension of a carrier fluid (paragraph 0069 – paragraph 0074).

In re claims 14-18, Yudasaka et al discloses the different printing processes (paragraph 0045 – paragraph 0075).

In re claims 19-20, Yudasaka et al discloses the electronic component is a transistor, capacitor, or a diode (Figure 5; Figure 6; Figure 7).

In re claims 22-26, Yudasaka et al discloses a method of manufacturing an electronic component comprising at least one n- or p-doped portion, comprising the steps of: co-depositing discrete nanoparticles of semi-conducting material as a solid in liquid suspension with a dopant on a substrate, the nanoparticles comprising silicon element

or germanium element; fusing in situ on the substrate the nanoparticles with one or more first laser pulses to form a continuous layer through a physical change of melting; and recrystallizing the continuous layer (paragraph 0004; paragraph 0045 – paragraph 0075).

In re claims 27-29, Yudasaka et al discloses the step of fusing and/or recrystallizing is carried out in a reducing atmosphere (paragraph 0065).

In re claim 30, Yudasaka et al discloses the electronic component is a transistor, capacitor, or a diode (Figure 5; Figure 6; Figure 7).

In re claims 63-64 and 68, Yudasaka et al discloses both a first semiconducting material and a second semiconducting material (paragraph 0045 – paragraph 0070; Example 1).

In re claim 71, Yudasaka et al discloses depositing nanoparticles on a further substrate, causing the nanoparticles to fuse and recrystallise to form a recrystallized film or layer (paragraph 0045 – paragraph 0070; Example 1).

In re claims 74-75, Yudasaka et al discloses a component using the above method (Example 1; Figure 5, Figure 6, Figure 7).

Claims 1-20, 22-30, 63-64, 68, 71, and 74-75 are rejected under 35 U.S.C. 102(b) as anticipated by or, in the alternative, under 35 U.S.C. 103(a) as obvious over Furusawa et al (WO 00/59044 – US Patent 6,518,087 is patent family member used for citation purposes).

In re claims 1-3, Furusawa et al discloses a method of manufacturing an electronic component comprising at least one n- or p-doped portion, comprising the steps of: co-depositing semi-conducting nanoparticles as a solid in liquid suspension and dopant on a substrate, the nanoparticles comprising silicon element or germanium element; fusing in situ on the substrate the nanoparticles by heating to form a continuous layer through a physical change of melting; and recrystallizing the continuous layer (column 9 – column 12).

In re claims 4-6, Furusawa et al discloses the step of fusing and/or recrystallizing is carried out in a reducing atmosphere (column 9 – column 12).

In re claims 7-10, Furusawa et al discloses the step of heating using laser pulses and cooling (column 9 – column 12).

In re claims 11-13, Furusawa et al discloses the nanoparticles are deposited in a suspension of a carrier fluid (column 9 – column 12).

In re claims 14-18, Furusawa et al discloses the different printing processes (column 9 – column 12).

In re claims 19-20, Furusawa et al discloses the electronic component is a transistor, capacitor, or a diode (Figure 3; Figure 4; Figure 5).

In re claims 22-26, Furusawa et al discloses a method of manufacturing an electronic component comprising at least one n- or p-doped portion, comprising the steps of: co-depositing discrete nanoparticles of semi-conducting material as a solid in liquid suspension with a dopant on a substrate, the nanoparticles comprising silicon element or germanium element; fusing in situ on the substrate the nanoparticles with one or more first laser pulses to form a continuous layer through a physical change of melting; and recrystallizing the continuous layer (column 9 – column 12).

In re claims 27-29, Furusawa et al discloses the step of fusing and/or recrystallizing is carried out in a reducing atmosphere (column 9 – column 12).

In re claim 30, Furusawa et al discloses the electronic component is a transistor, capacitor, or a diode (Figure 3; Figure 4; Figure 5).

In re claims 63-64 and 68, Furusawa et al discloses both a first semiconducting material and a second semiconducting material (column 9 – column 12; Example 1).

In re claim 71, Furusawa et al discloses depositing nanoparticles on a further substrate, causing the nanoparticles to fuse and recrystallise to form a recrystallized film or layer (column 9 – column 12; Example 1).

In re claims 74-75, Furusawa et al discloses a component using the above method (Example 1; Figure 3; Figure 4; Figure 5).

Response to Arguments

Applicant's arguments filed September 24, 2008 have been fully considered but they are not persuasive.

In response to applicant's argument that Yudasaka and Furusawa do not disclose a method of co-depositing inorganic semi-conducting nanoparticles as a solid in liquid suspension, examiner asserts, for example, that the silicon compounds disclosed in Yudasaka are "solid nanoparticles". Compounds 1-5 of Yudasaka are solid nanoparticles because they consist of cyclical silicon compounds of, for example, 6-14 silicon atoms comprising "nanoparticles" solid. There is no specific structural recitation in regards to the nanoparticles in the claim that would distinguish over the solid nanoparticles of Yudasaka. In addition, applicant argues, for example, that passages in Yudasaka disclose a solution of a silicone compound. Examiner asserts that the terms "in liquid suspension" and "solution" are not distinguishable from one another. Thus, the claimed invention is not patentably distinct over the applied prior arts of record.

In response to applicant's argument that the references fail to show certain features of applicant's invention, it is noted that the features upon which applicant relies (i.e., the nanoparticles consisting only of silicon element or germanium element) are not recited in the rejected claim(s). Although the claims are interpreted in light of the specification, limitations from the specification are not read into the claims. See *In re Van Geuns*, 988 F.2d 1181, 26 USPQ2d 1057 (Fed. Cir. 1993).

Conclusion

THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to ANTHONY HO whose telephone number is (571)270-1432. The examiner can normally be reached on M-Th: 10:30AM-9:00PM EST.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kenneth Parker can be reached on 571-272-2298. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/A. H./
Examiner, Art Unit 2815

/Jerome Jackson Jr./
Primary Examiner, Art Unit 2815